



Material Composition Declaration

EPC2012C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	2.8 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.4719	89.26	91.81	892565
	Silicon oxide	7631-86-9	0.0095	0.34		3447
	Silicon nitride	12033-89-5	0.0030	0.11		1072
	Gallium nitride	25617-97-4	0.0180	0.65		6492
	Aluminum	7429-90-5	0.0184	0.67		6659
	Aluminum nitride	24304-00-5	0.0044	0.16		1593
	Titanium	7440-32-6	0.0004	0.01		130
	Titanium nitride	25583-20-4	0.0016	0.06		570
	Copper	7440-50-8	0.0006	0.02		222
	Tungsten	7440-33-7	0.0003	0.01		115
	Polyimide		0.0144	0.52		5193
Under Bump Metal	Titanium	7440-32-6	0.0004	0.01	1.10	130
	Nickel	7440-02-0	0.0107	0.39		3868
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0194	0.70		7003
Solder Bump	Tin	7440-31-5	0.1916	6.92	7.09	69169
	Silver	7440-22-4	0.0049	0.18		1774
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			2.8	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.